

DESCRIPTION

The R8A66162SP is a semiconductor integrated circuit for LED array driver with 32-bit serial-input, parallel - output shift register, equipped with direct set input and output latches.

The R8A66162SP guarantees sufficient 24mA (Vcc=5.0V case) output current to drive anode common LED, allowing 32-bit simultaneous and continuous current output. The parallel outputs are open-drain outputs.

In addition, as this product has been designed in complete CMOS, power consumption can be greatly reduced when compared with conventional BIPOLAR or Bi-CMOS products. Furthermore, pin layout ensures the realization of an easy printed circuit. R8A66162SP is the succession product of M66313FP.

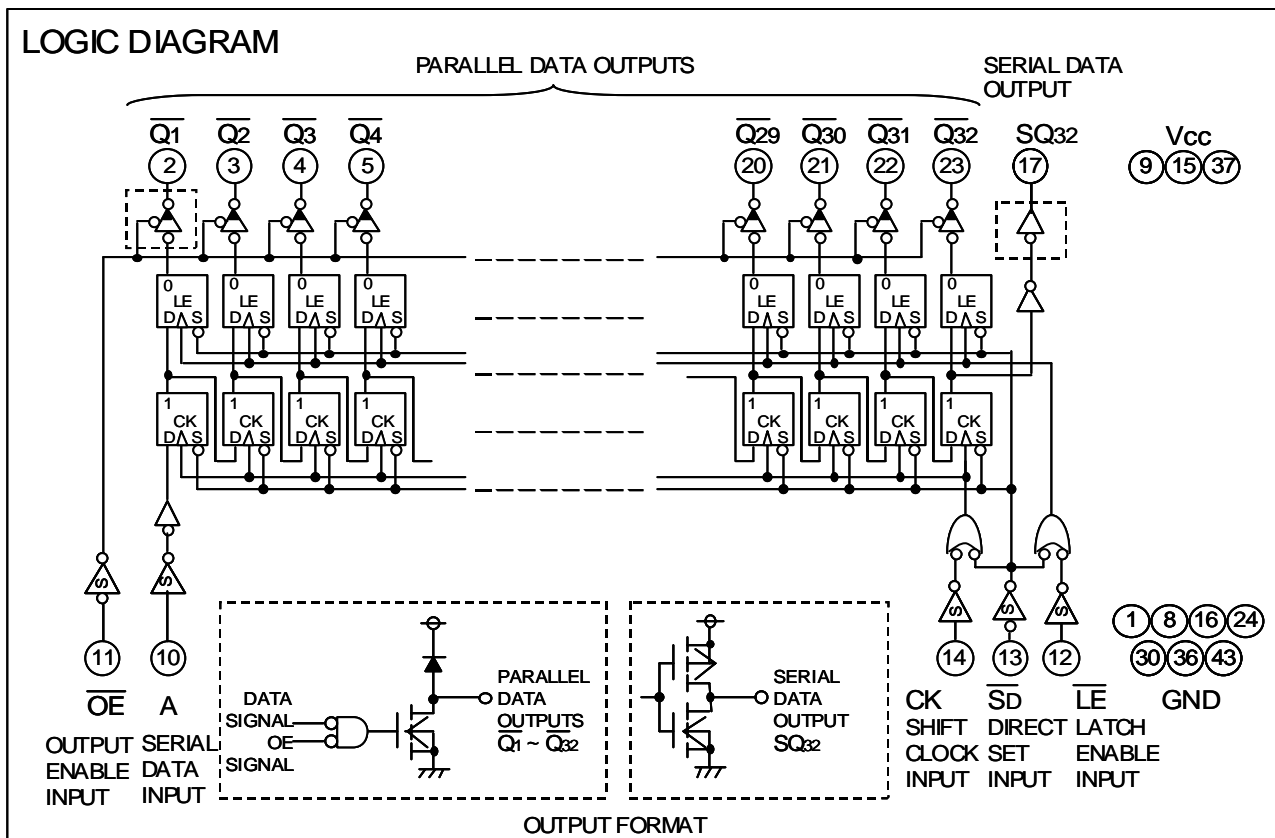
FEATURES

- Anode common LED drive
- Vcc 5V or 3.3V single power supply
- High output current: All parallel outputs $\overline{Q_1} \sim \overline{Q_{32}}$ IOL=24mA (at VCC=5.0V), IOL=12mA (at VCC=3.3V), LEDs can be turned on simultaneously.
- Low power dissipation: 200uW/package (max) (VCC=5.0V, Ta=25°C, quiescent state)
- High noise margin: Employment of Schmitt-trigger circuit on all inputs allows application with long wiring.
- Direct set input (\overline{SD})
- Open-drain output ($\overline{Q_1} \sim \overline{Q_{32}}$)
- Serial data output for cascading (SQ32)
- Wide operating temperature range (Ta=-40°C~+85°C)
- Pin configuration for easy layout on PCB. (Pin configuration allows easy cascade connection or LED connection)

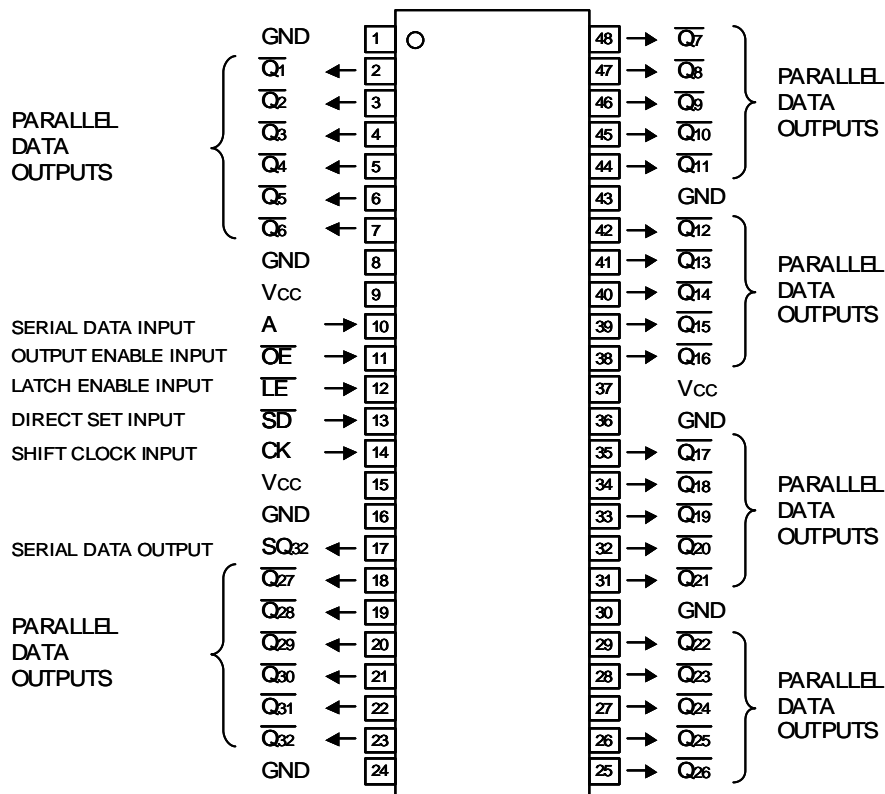
APPLICATION

- LED array drive, The various LED display modules
- PPC, Printer, VCR, Mini-compo, Button-Telephone etc. All of LED display equipments

BLOCK DIAGRAM



PIN CONFIGURATION (TOP VIEW)



FUNCTIONAL DESCRIPTION

The employment of silicon gate CMOS process of the R8A66162SP guarantees low power dissipation and maintains high noise margin as well as high output current and high speed required to drive LEDs. Each shift register bit consists of a flip-flop for shifting and an output latch.

The shift operation takes place when the shift clock input CK changes from low-level to high-level.

The serial data input A corresponds to the data input of the first-stage shift register, and the shift register is shifted in sequence when a pulse is applied to CK.

If the latch-enable input LE is turned high-level, the content of the shift register at that instant is latched.

The parallel data outputs Q₁~Q₃₂ are open-drain outputs.

To expand the number of bits, use the serial data output SQ₃₂ which shows the output of the shift register of the 32nd bit.

If the direct set input SD is turned low-level, Q₁~Q₃₂ and SQ₃₂ are set. Then shift register and latches are set. If the high-level input is applied to the output enable input OE, Q₁~Q₃₂ are set to the high-impedance state, but SQ₃₂ is not set to the high-impedance state. The shift operation is not affected when OE is changed.

FUNCTION TABLE (Note: 1)

OPERATION MODE	INPUT					PARALLEL OUTPUTS																																SERIAL OUTPUT SQ ₃₂	
	\overline{SD}	CK	\overline{LE}	A	\overline{OE}	$\overline{Q_1}$	$\overline{Q_2}$	$\overline{Q_3}$	$\overline{Q_4}$	$\overline{Q_5}$	$\overline{Q_6}$	$\overline{Q_7}$	$\overline{Q_8}$	$\overline{Q_9}$	$\overline{Q_{10}}$	$\overline{Q_{11}}$	$\overline{Q_{12}}$	$\overline{Q_{13}}$	$\overline{Q_{14}}$	$\overline{Q_{15}}$	$\overline{Q_{16}}$	$\overline{Q_{17}}$	$\overline{Q_{18}}$	$\overline{Q_{19}}$	$\overline{Q_{20}}$	$\overline{Q_{21}}$	$\overline{Q_{22}}$	$\overline{Q_{23}}$	$\overline{Q_{24}}$	$\overline{Q_{25}}$	$\overline{Q_{26}}$	$\overline{Q_{27}}$	$\overline{Q_{28}}$	$\overline{Q_{29}}$	$\overline{Q_{30}}$	$\overline{Q_{31}}$	$\overline{Q_{32}}$		
SET	L	X	X	X	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	H
SHIFT	H		L	H	L	L	Q ⁰ ₁	Q ⁰ ₂	Q ⁰ ₃	Q ⁰ ₄	Q ⁰ ₅	Q ⁰ ₆	Q ⁰ ₇	Q ⁰ ₈	Q ⁰ ₉	Q ⁰ ₁₀	Q ⁰ ₁₁	Q ⁰ ₁₂	Q ⁰ ₁₃	Q ⁰ ₁₄	Q ⁰ ₁₅	Q ⁰ ₁₆	Q ⁰ ₁₇	Q ⁰ ₁₈	Q ⁰ ₁₉	Q ⁰ ₂₀	Q ⁰ ₂₁	Q ⁰ ₂₂	Q ⁰ ₂₃	Q ⁰ ₂₄	Q ⁰ ₂₅	Q ⁰ ₂₆	Q ⁰ ₂₇	Q ⁰ ₂₈	Q ⁰ ₂₉	Q ⁰ ₃₀	Q ⁰ ₃₁	q ⁰ ₃₁	
	H		L	L	L	Z	Q ⁰ ₁	Q ⁰ ₂	Q ⁰ ₃	Q ⁰ ₄	Q ⁰ ₅	Q ⁰ ₆	Q ⁰ ₇	Q ⁰ ₈	Q ⁰ ₉	Q ⁰ ₁₀	Q ⁰ ₁₁	Q ⁰ ₁₂	Q ⁰ ₁₃	Q ⁰ ₁₄	Q ⁰ ₁₅	Q ⁰ ₁₆	Q ⁰ ₁₇	Q ⁰ ₁₈	Q ⁰ ₁₉	Q ⁰ ₂₀	Q ⁰ ₂₁	Q ⁰ ₂₂	Q ⁰ ₂₃	Q ⁰ ₂₄	Q ⁰ ₂₅	Q ⁰ ₂₆	Q ⁰ ₂₇	Q ⁰ ₂₈	Q ⁰ ₂₉	Q ⁰ ₃₀	Q ⁰ ₃₁	q ⁰ ₃₁	
LATCH	H	X	H	X	L	Q ⁰ ₁	Q ⁰ ₂	Q ⁰ ₃	Q ⁰ ₄	Q ⁰ ₅	Q ⁰ ₆	Q ⁰ ₇	Q ⁰ ₈	Q ⁰ ₉	Q ⁰ ₁₀	Q ⁰ ₁₁	Q ⁰ ₁₂	Q ⁰ ₁₃	Q ⁰ ₁₄	Q ⁰ ₁₅	Q ⁰ ₁₆	Q ⁰ ₁₇	Q ⁰ ₁₈	Q ⁰ ₁₉	Q ⁰ ₂₀	Q ⁰ ₂₁	Q ⁰ ₂₂	Q ⁰ ₂₃	Q ⁰ ₂₄	Q ⁰ ₂₅	Q ⁰ ₂₆	Q ⁰ ₂₇	Q ⁰ ₂₈	Q ⁰ ₂₉	Q ⁰ ₃₀	Q ⁰ ₃₁	q ⁰ ₃₂		
OUTPUT DISABLE	X	X	X	X	H	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	q ⁰ ₃₂	

- Note 1.
- $\overline{}$: Transition from low-to-high-level
 - Q⁰ : Shows the status of output Q before CK input changes
 - X : Irrelevant
 - q⁰ : The content of shift register before CK changes
 - q : The content of shift register
 - Z : High-impedance state

ABSOLUTE MAXIMUM RATINGS (Ta=-40~85°C, unless otherwise noted)

Symbol	Parameter	Conditions	Ratings	Unit
V _{cc}	Supply voltage		-0.5~+7.0	V
V _I	Input voltage		-0.5~V _{cc} +0.5	V
V _O	Output voltage		-0.5~V _{cc} +0.5	V
I _O	Output current per output pin	$\overline{Q_1} \sim \overline{Q_{32}}$	50	mA
		SQ ₃₂	±25	
I _{cc}	Supply/GND current	V _{cc} , GND	-920, +20	mA
P _d	Power dissipation		650	mW
T _{stg}	Storage temperature range		-65~150	°C

RECOMMENDED OPERATING CONDITIONS (Ta=-40~85°C, unless otherwise noted)

Symbol	Parameter	Limits			Unit	
		Min.	Typ.	Max.		
V _{cc}	Supply voltage	5.0V support	4.5	5.0	5.5	V
		3.3V support	3.0	3.3	3.6	V
V _I	Input voltage	0		V _{cc}	V	
V _O	Output voltage	0		V _{cc}	V	
T _{opr}	Operating temperature range	-40		85	°C	

ELECTRICAL CHARACTERISTICS

■ 5.0V version support specifications (Ta=-40~85°C, Vcc=4.5V~5.5V, unless otherwise noted)

Symbol	Parameter		Test conditions		Limits			Unit
					Min.	Typ.	Max.	
V _{T+}	Positive going threshold voltage				0.35xV _{cc}		0.70xV _{cc}	V
V _{T-}	Negative going threshold voltage				0.20xV _{cc}		0.55xV _{cc}	V
V _{OH}	High level output voltage	SQ ₃₂	V _I =V _{T+} , V _{T-} V _{cc} =4.5V	I _{OH} =-20uA I _{OH} =-4mA	V _{cc} -0.1 3.66			V
V _{OL}	Low level output voltage	Q ₁ ~Q ₃₂	V _I =V _{T+} , V _{T-} V _{cc} =4.5V	I _{OL} =20uA			0.10	V
				I _{OL} =24mA			0.50	
				I _{OL} =28mA			0.55 _(Note2)	
		SQ ₃₂		I _{OL} =20uA			0.10	
				I _{OL} =4mA			0.53	
I _{IH}	High level input current		V _I =V _{cc} V _{cc} =5.5V				5	uA
I _{IL}	Low level input current		V _I =GND V _{cc} =5.5V				-5	uA
I _O	Maximum output leakage current	Q ₁ ~Q ₃₂	V _I =V _{T+} , V _{T-} V _{cc} =5.5V	V _O =V _{cc}			10	uA
				V _O =GND			-10	
I _{cc}	Quiescent supply current		V _I =V _{cc} , GND V _{cc} =5.5V				400	uA

Note2 : Ta = -40~70°C

■ 3.3V version support specifications (Ta=-40~85°C, Vcc=3.0V~3.6V, unless otherwise noted)

Symbol	Parameter		Test conditions		Limits			Unit
					Min.	Typ.	Max.	
V _{T+}	Positive going threshold voltage				0.35xV _{cc}		0.70xV _{cc}	V
V _{T-}	Negative going threshold voltage				0.20xV _{cc}		0.55xV _{cc}	V
V _{OH}	High level output voltage	SQ ₃₂	V _I =V _{T+} , V _{T-} V _{cc} =3.0V	I _{OH} =-20uA I _{OH} =-2mA	V _{cc} -0.1 2.60			V
V _{OL}	Low level output voltage	Q ₁ ~Q ₃₂	V _I =V _{T+} , V _{T-} V _{cc} =3.0V	I _{OL} =20uA			0.10	V
				I _{OL} =12mA			0.54	
		SQ ₃₂		I _{OL} =20uA			0.10	
				I _{OL} =2mA			0.40	
I _{IH}	High level input current		V _I =V _{cc} V _{cc} =3.6V				5	uA
I _{IL}	Low level input current		V _I =GND V _{cc} =3.6V				-5	uA
I _O	Maximum output leakage current	Q ₁ ~Q ₃₂	V _I =V _{T+} , V _{T-} V _{cc} =3.6V	V _O =V _{cc}			10	uA
				V _O =GND			-10	
I _{cc}	Quiescent supply current		V _I =V _{cc} , GND V _{cc} =3.6V				400	uA

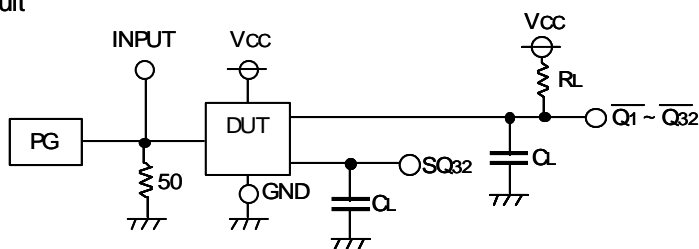
SWITCHING CHARACTERISTICS (Ta=-40~85°C, Vcc=5.0V or 3.3V, unless otherwise noted)

Symbol	Parameter	Test conditions	5.0V specification			3.3V specification			Unit	
			Min.	Typ.	Max.	Min.	Typ.	Max.		
f _{max}	Maximum clock frequency	C _L =50pF R _L =1kΩ (Note3)			4			3.3	MHz	
tPZL	Output "Z-L" and "L-Z" propagation time		CK-Q ₁ ~Q ₃₂ (Turned on)			200			220	ns
tPLZ			CK-Q ₁ ~Q ₃₂ (Turned off)			250			270	ns
tPLH	Output "L-H" and "H-L" propagation time		CK-SQ ₃₂			125			150	ns
tPHL						125			150	ns
tPZL	Output "Z-L" propagation time		S _D -Q ₁ ~Q ₃₂ (Turned on)			200			220	ns
tPLH	Output "L-H" propagation time		S _D -SQ ₃₂			125			150	ns
tPZL	Output "Z-L" and "L-Z" propagation time		LE-Q ₁ ~Q ₃₂ (Turned on)			125			150	ns
tPLZ			LE-Q ₁ ~Q ₃₂ (Turned off)			200			220	ns
tPZL	Output "Z-L" and "L-Z" propagation time		OE-Q ₁ ~Q ₃₂ (Turned on)			125			150	ns
tPLZ		OE-Q ₁ ~Q ₃₂ (Turned off)			200			220	ns	
C _I	Input capacitance				10			10	pF	
C _O	Output capacitance	OE=Vcc			15			15	pF	

TIMING REQUIREMENTS (Ta=-40~85°C, Vcc=5.0V or 3.3V, unless otherwise noted)

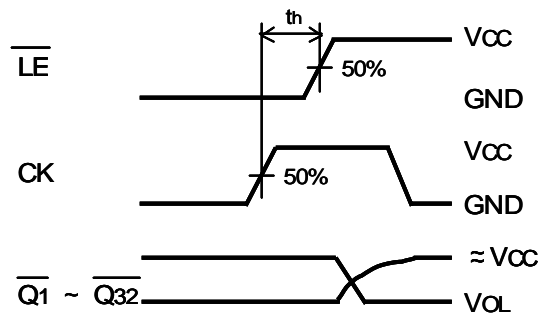
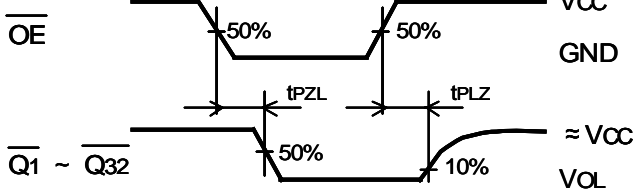
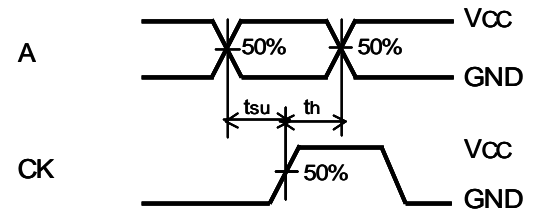
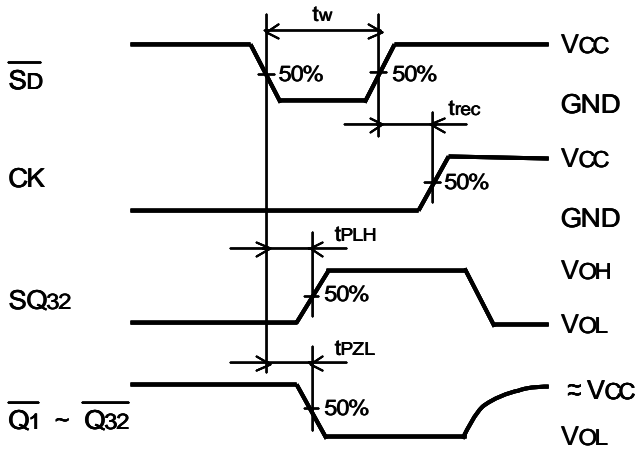
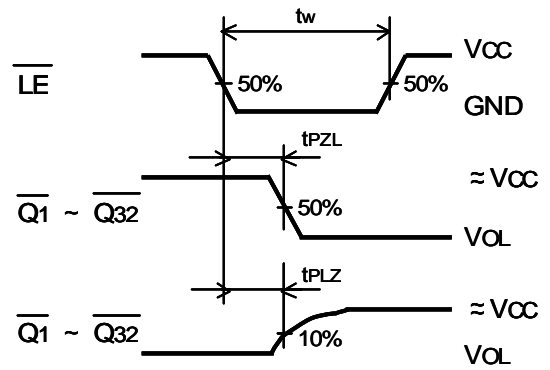
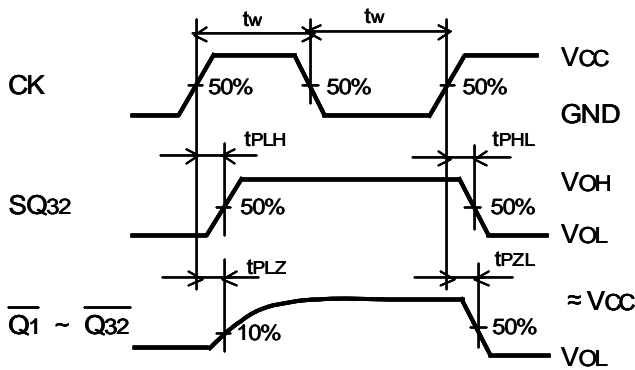
Symbol	Parameter	Test conditions	5.0V specification			3.3V specification			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
t _w	CK, LE, S _D pulse width	(Note3)	125			150			ns
t _{su}	Setup time A to CK		125			150			ns
t _h	Hold time A to CK		15			20			ns
	Hold time LE to CK		70			80			ns
t _{rec}	Recovery time CK to S _D		70			80			ns

Note3. Test circuit



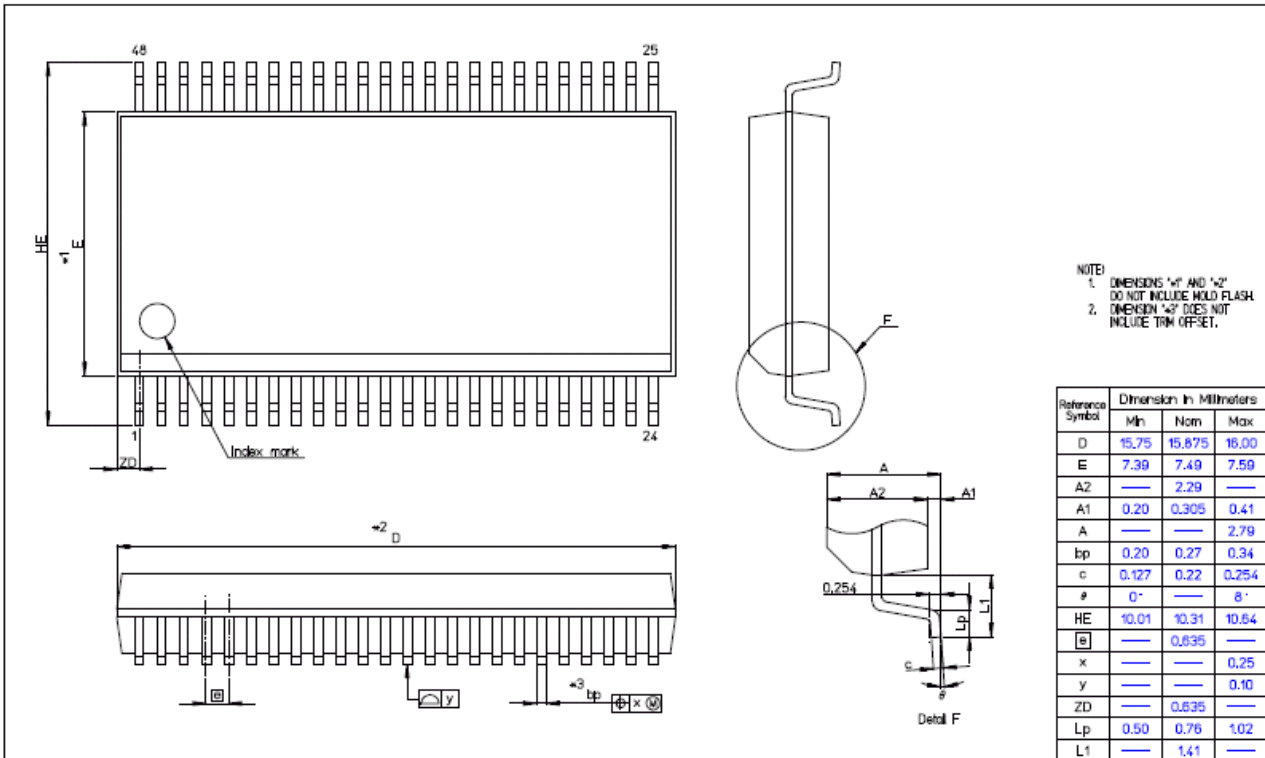
- (1) The pulse generator(PG) has the following characteristics(10%~90%):tr=6ns,tf=6ns
- (2) The capacitance CL includes stray wiring capacitance and the probe input capacitance.

TIMING DIAGRAM



PACKAGE OUTLINE

Package 48pin SSOP	RENESAS Code PRSP0048ZB-A	Previous Code 48P2X-A
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